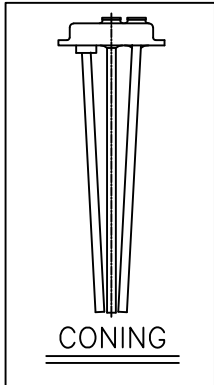
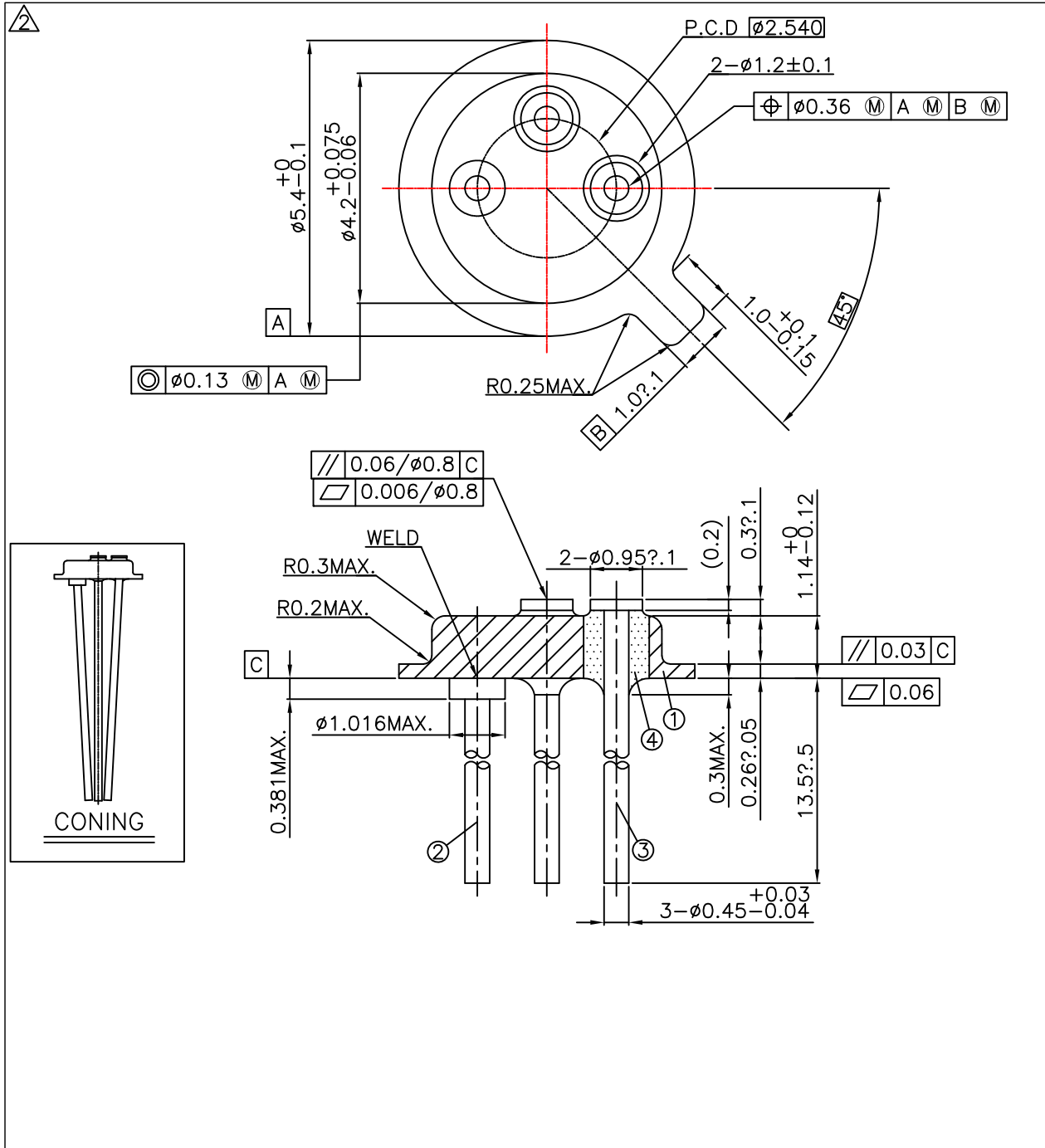


SSM P/N HDR04625



REV	DATE	DSGN	CHECK	APPR	DESCRIPTION	ITEM	DESCRIPTION	DWG NO.	MATERIAL	QTY
02	'17.02.10	CW.PARK	TW.KANG	CH.KANG	Packaging method add(4)	1	EYELET		KOVAR	1
						2	LEAD		KOVAR	1
						3	LEAD		KOVAR	2
						4	GLASS		HARD GLASS	2
NOTE: SPECTRUM SEMICONDUCTOR MATERIALS, INC.										
See notes 1.										
DATE DESIGNED DRAWN CHECKED APPR'D TITLE										
'17.02.03 CW.PARK CW.PARK TW.KANG CH.KANG TO-46/2P3L HDR										
KOREA SHINKO MICROELECTRONICS CO.,LTD.						PROJ 3RD ANGLE	SCALE 10:1	DRAWING NO. CH2017_018 1/3		

SSM P/N HDR04625



NOTES.

1. Finish
Full gold 1.27umMIN. over 2.54umMIN. Electrolytic nickel under plating.
 - 1) Plating thickness : Controlled on top of the post.
 - 2) Measuring method : X-ray fluorescence machine.



2. Packaging method.
 - 2-1. Packaging material

	Transportation box	Inside box	Tray	Vacuum bag	Air cap	Silicagel
Packing material	Carton box	Carton box	CBX-1394	Plastic pack	Air cap	Silicagel
Size	490X420X270	485X415X65	190X100X18	300X400X0.08	210X310X15	4g
Quantity(16,000pcs)	1	4	96	8	Suitable	Suitable

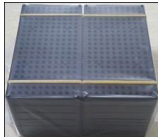
- 2-2. Packaging method
 - 1) Put 200 pcs parts in carrier.



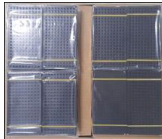
- 2) The carrier containing the parts is piled 5 carrier, and empty carrier is put on the top.(total 6 carrier)



- 3) The carrier containing a parts of a 12 pile is put into Plastic bag with silica gel.



- 4) Operate 1) to 3) method 8 times repeatedly. (vacuumed Plastic bags – total of 8)
- 5) 6 Plastic bags are put inside box.



02	'17.02.10	CW.PARK	TW.KANG	CH.KANG	Packaging method add(2)		MATERIAL	FINISH	NOTE
REV	DATE	DSGN	CHECK	APPR	DESCRIPTION				
	DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE			
	'17.02.03	CW.PARK	CW.PARK	TW.KANG	CH.KANG	TO-46/2P3L HDR			
KOREA SHINKO MICROELECTRONICS CO.,LTD.						PROJ 3RD ANGLE	SCALE	DRAWING NO.	CH2017_018 2/3



SSM P/N HDR04625

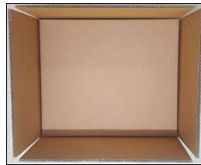


6) Put a inside box on the top of inside box.



7) Operate 6) method 2 times repeatedly.
(Inside Carton box – total of 2)

8) Put 2 inside box in transportation box.
(1)First floor : 8,000pcs/4 Plastic bags.
(2)Second floor : 8,000pcs/4 Plastic bags.
[Total : 16,000pcs/Transportation box]



9) Tapping the outside box.



02	'17.02.10	CW.PARK	TW.KANG	CH.KANG	Packaging method add(1)	MATERIAL	FINISH	NOTE
REV	DATE	DSGN	CHECK	APPR	DESCRIPTION			
	DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE		
	'17.02.03	CW.PARK	CW.PARK	TW.KANG	CH.KANG	TO-46/2P3L HDR		
KOREA SHINKO MICROELECTRONICS CO.,LTD.						PROJ 3RD ANGLE	SCALE	DRAWING NO. CH2017_018 3/3